

[10191/2235]

H/A  
5/6/13  
WS**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s) : GOEBEL et al.  
Serial No. : To Be Assigned  
Filed : Herewith  
For : SEMICONDUCTOR ARRANGEMENT AND  
METHOD OF MANUFACTURE  
Examiner : To Be Assigned  
Group Art Unit : To Be Assigned

Assistant Commissioner  
for Patents  
Washington, D.C. 20231

**PRELIMINARY AMENDMENT**

SIR:

Please amend the above-identified application before examination as follows:

**IN THE SPECIFICATION AND ABSTRACT:**

In accordance with 37 C.F.R. § 1.121(b)(3), a Substitute Specification (including the Abstract but without claims) accompanies this response. It is respectfully requested that the Substitute Specification be entered to replace the Specification of record.

**IN THE CLAIMS:**

Without prejudice, please cancel original claims 1-7 and cancel substitute claims 1-3. Please add new claims 8-13 as shown below:

--8. (New) A semiconductor chip comprising:

A<sup>1</sup> a first layer of a first conductivity type having at least two partial layers, a first